PATENT S/N Unknown

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Kishore K. Chakravorty

Examiner: Unknown

Serial No.:

Unknown

Group Art Unit: Unknown

Filed:

Herewith

Docket: 884.267US1

Title:

ELECTRONIC ASSEMBLY COMPRISING INTERPOSER WITH

EMBEDDED CAPACITORS AND METHODS OF MANUFACTURE

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents Washington, D.C. 20231

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 et. seq., the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicant respectfully requests that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicant further request that a copy of the 1449 form, initialed by the Examiner to indicate that all listed citations have been considered, be returned with the next official communication.

Please charge any additional fees or credit any overpayment to Account No. 19-0743.

The Examiner is invited to contact the Applicant's Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

KISHORE K. CHAKRAVORTY

By his Representatives,

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

P.O. Box 2938

Minneapolis, MN 55402

(612) 349-9592

By

Ann M. McCrackin Reg. No. 42,858

CERTIFICATE UNDER 37 CFR 1.10:

"Express Mail" mailing label number: EL600376773US

Date of Deposit: July 31, 2000

I hereby certify that this paper or fee is being deposited with the United States Postal Service "Express May Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Shawn Hise

Name

Signature

#4

Form 1449*

INFORMATION DISCLOSURE STATEMENT
BY APPLICANT
(Use several sheets if necessary)

Atty. Docket No.: 884.267US1

Atty. Docket No.: 884.267US1

Serial No. Unknown

Applicant: Kishore K. Chakravorty

Filing Date: Herewith

Group: Unknown

U.S. PATENT DOCUMENTS

U.S. PATENT DOCUMENTS								
**Examiner Initial	Document Number	Date	Name		lass	Subclass	Filing Date O If Appropriate 🛏	
							s. 8705	
	FOREIGN PATENT DOCUMENTS							
**Examiner Initial	Document Number	Date	Country	(lass	Subclass	Translation () Yes No ()	
							ja	
**Examiner Initial								
Amey, D., et al., "Advances in MCM Ceramics", Solid State Technology 143-146, (1997)						nnology,		
	from 1 mHz	Baniecki, J., et al., "Dielectric Relaxation of Ba0.7 Sr0.3 TiO3 Thin Films from 1 mHz to 20 GHz", Appl. Phys. Letter 72(4), 1998 American Institute of Physics, 198-500, (Jan. 1998)						
	Buried in	Chan, Y., et al., "Fabrication and Characterization of Multilayer Capacitors Buried in a Low Temperature Co-Fired Ceramic Substrate", <u>Active and Passive Elec. Comp. Vol. 20</u> , 215-224, (1998)						
	in LTCC Te	Choi, K.L., et al., "Characterization of Embedded Passives Using Macromodels in LTCC Technology", IEEE Transactions on Components, Packaging, and Manufacturing Technology, Vol. 21, 258-268, (Aug. 1998) Eurskens, W., et al., "Design and Performance of UHF Band Inductors, Capacitors and Resonators Using LTCC Technology for Mobile Communication Systems", 1998 IEEE MTT-S Digest, 1285-1288, (1998)						
	Capacitors							
	Koschmieder, T., et al., "Ceramic Substrate Thickness, Test Board Thickness, and Part Spacing: A Screening Doe", <u>Proceedings of SMTA International Conference</u> , 6 pgs., (Sept. 1999)							
			pe Casting: Past, <u>letin</u> , 82-86, (O		tenti	al", The	American	
	SrTiO3 Cap	acitors f	ll., "3.5 V Operat for 1.95 GHz Wide-B 450, (1998)	ion Driver-Ar and CDMA Cell	mplif lular	ier MMIC Phones"	Utilizing 1998 IEEE	
	Rector, Jr., J., et al., "Integrated and Integral Passive Components: A Technology Roadmap", 1997 Electronic Components and Technology Conference, 713-723, (1997)							

Examiner	Date	Considered

^{*}Substitute Disclosure Statement Form (PTO-1449)

^{**}EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Atty. Docket No.: 884.267US1 Serial No. Unknown

RE STATEMENT
NT

Applicant: Kishore K. Chakravorty

Group: Unknown

INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)

OTHER DOCUMENTS

Filing Date: Herewith

**Examiner Initial

Form 1449*

(Including Author, Title, Date, Pertinent Pages, Etc.)

Scrantom, S., et al., "Manufacture of Embedded Integrated Passive Components into Low Temperature Co-Fired Ceramic Systems", 1998 International Symposium on Microelectronics, 459-466, (1998)
Sugai, K., et al., "Multilayer Alumina Substrates for ECU", <u>1998 IEEE/CPMT</u> Berlin Int'l Electronics Manufacturing Technology Symposium, 109-112, (1998)
Tok, A.I., et al., "Tape Casting of Composite Ceramic Substrates Using Hollow Micro-Speherical Powders", <u>Processing and Fabrication of Advanced Materials VII</u> , Proceedings of a Symposium organized by: The Minerals, Metals & Materials Society (TMS), Warrendale, PA, USA, 451-461, (Oct. 1998)
Ueda, T., et al., "GaAs MMIC Chip-sets for Mobile Communication Systems with On-chip Ferroelectric Capacitors", <u>Integrated Ferroelectrics, Vol. 7</u> , 45-60, (1995)
Williamson, III, W., et al., "High Frequency Dielectric Properties of PLZT Thin Films", Integrated Ferroelectrics, Vol. 17, 197-203, (1997)
Yamasaki, K., et al., "Solder Column Interposer Grid Array - Improved CBGA Reliability", 1-9,
Yao, K., et al., "Improved Preparation Procedure and Properties for a Multilayer Piezoelectric Thick-Film Actuator", <u>Sensors and Actuators A 71</u> , 139-143, (1998)

Examiner	Date	Considered
	Į	

^{*}Substitute Disclosure Statement Form (PTO-1449)

^{**}EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609, Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.